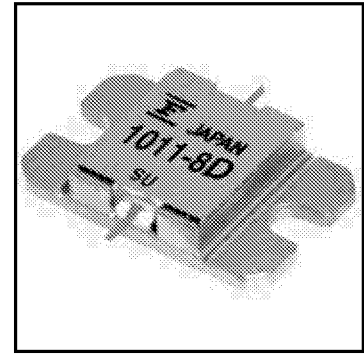


FEATURES

- High Output Power: $P_{1dB} = 38.5\text{dBm}$ (Typ.)
- High Gain: $G_{1dB} = 5.0\text{dB}$ (Typ.)
- High PAE: $\eta_{add} = 22\%$ (Typ.)
- Low $IM_3 = -45\text{dBc}@P_o = 28\text{dBm}$
- Broad Band: 10.7 ~ 11.7GHz
- Impedance Matched $Z_{in}/Z_{out} = 50\Omega$
- Hermetically Sealed



DESCRIPTION

The FLM1011-8D is a power GaAs FET that is internally matched for standard communication bands to provide optimum power and gain in a 50 ohm system.

Fujitsu's stringent Quality Assurance Program assures the highest reliability and consistent performance.

ABSOLUTE MAXIMUM RATING (Ambient Temperature $T_a=25^\circ\text{C}$)

Item	Symbol	Condition	Rating	Unit
Drain-Source Voltage	V_{DS}		15	V
Gate-Source Voltage	V_{GS}		-5	V
Total Power Dissipation	P_T	$T_C = 25^\circ\text{C}$	42.8	W
Storage Temperature	T_{stg}		-65 to +175	$^\circ\text{C}$
Channel Temperature	T_{ch}		175	$^\circ\text{C}$

Fujitsu recommends the following conditions for the reliable operation of GaAs FETs:

1. The drain-source operating voltage (V_{DS}) should not exceed 10 volts.
2. The forward and reverse gate currents should not exceed 16.0 and -4.4 mA respectively with gate resistance of 100 Ω .

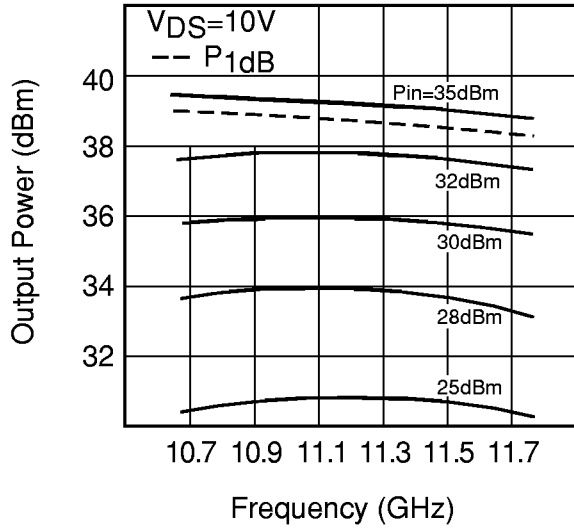
ELECTRICAL CHARACTERISTICS (Ambient Temperature $T_a=25^\circ\text{C}$)

Item	Symbol	Test Conditions	Limit			Unit
			Min.	Typ.	Max.	
Saturated Drain Current	I_{DSS}	$V_{DS} = 5\text{V}, V_{GS} = 0\text{V}$	-	3600	5400	mA
Transconductance	g_m	$V_{DS} = 5\text{V}, I_{DS} = 2200\text{mA}$	-	2000	-	mS
Pinch-off Voltage	V_p	$V_{DS} = 5\text{V}, I_{DS} = 180\text{mA}$	-1.0	-2.0	-3.5	V
Gate Source Breakdown Voltage	V_{GSO}	$I_{GS} = -180\mu\text{A}$	-5	-	-	V
Output Power at 1dB G.C.P.	P_{1dB}	$V_{DS} = 10\text{V},$ $I_{DS} = 0.6 I_{DSS}$ (Typ.), $f = 10.7 \sim 11.7 \text{GHz},$ $Z_S = Z_L = 50 \text{ohm}$	37.5	38.5	-	dBm
Power Gain at 1dB G.C.P.	G_{1dB}		4.0	5.0	-	dB
Drain Current	I_{dsr}		-	2200	2600	mA
Power-added Efficiency	η_{add}		-	22	-	%
Gain Flatness	ΔG		-	-	± 0.6	dB
3rd Order Intermodulation Distortion	IM_3	$f = 11.7 \text{GHz}, \Delta f = 10 \text{MHz}$ 2-Tone Test $P_{out} = 28\text{dBm S.C.L.}$	-42	-45	-	dBc
Thermal Resistance	R_{th}	Channel to Case	-	3.0	3.5	$^\circ\text{C/W}$

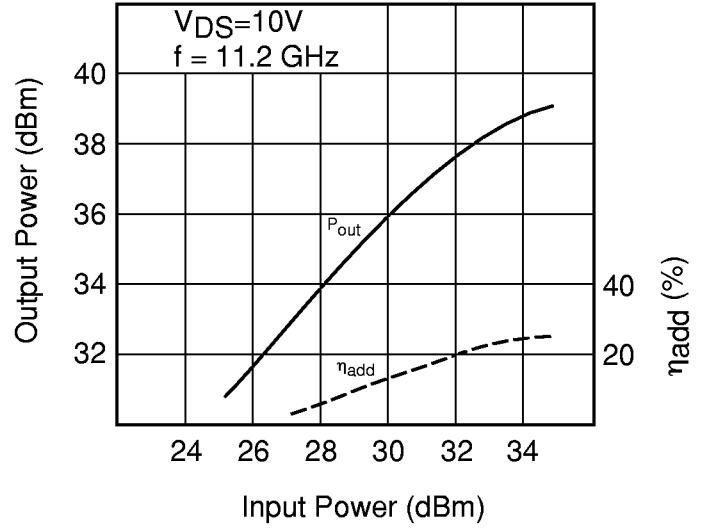
CASE STYLE: IB

G.C.P.: Gain Compression Point, S.C.L.: Single Carrier Level

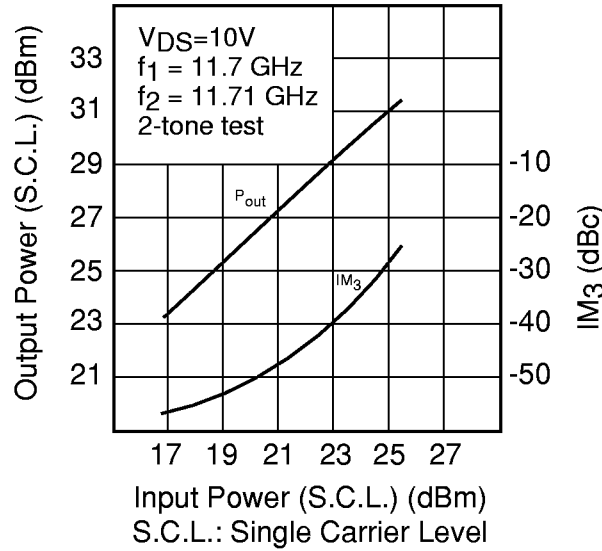
OUTPUT POWER vs. FREQUENCY



OUTPUT POWER vs. INPUT POWER

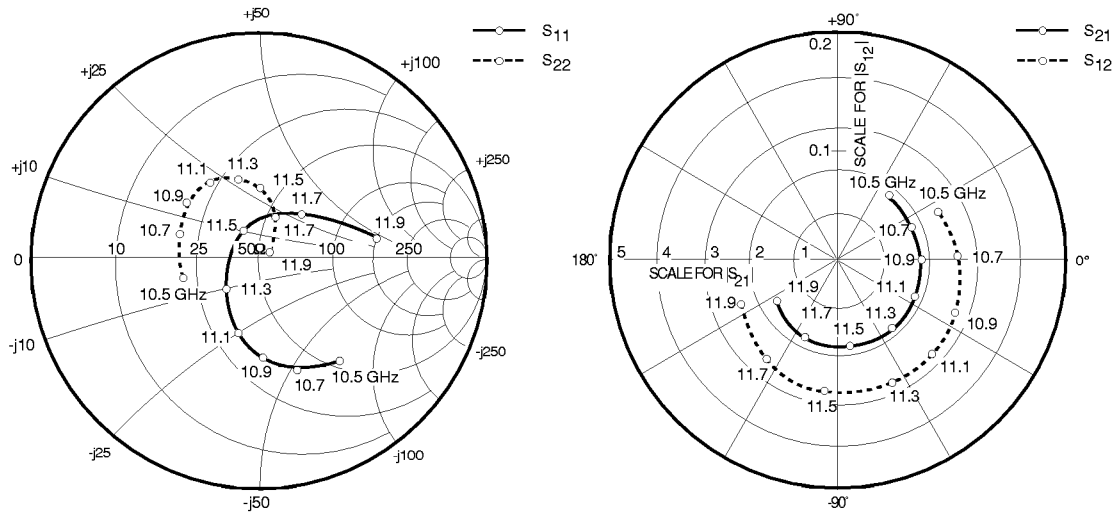


OUTPUT POWER & IM₃ vs. INPUT POWER



FLM1011-8D

Internally Matched Power GaAs FETs



S-PARAMETERS

$V_{DS} = 10V, I_{DS} = 2200mA$

FREQUENCY (MHZ)	S11		S21		S12		S22	
	MAG	ANG	MAG	ANG	MAG	ANG	MAG	ANG
10500	.55	-49	1.77	46	.10	25	.39	-168
10700	.50	-68	1.80	22	.10	2	.44	165
10900	.43	-88	1.82	-1	.11	-22	.46	144
11100	.33	-109	1.82	-25	.11	-46	.44	126
11300	.19	-142	1.83	-52	.11	-70	.41	110
11500	.11	112	1.87	-81	.11	-98	.32	87
11700	.32	42	1.78	-114	.10	-128	.18	61
11900	.54	11	1.56	-146	.09	-159	.06	23

Case Style "IB"
Metal-Ceramic Hermetic Package

